



PF06N01 V0 Preliminary
Product Specification

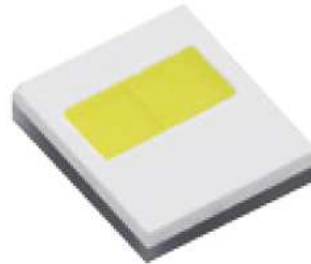
Approval Sheet

PF06N01 V0

Product Specification

RoHS

Product	3238 White LED
Part Number	PF06N01
Issue Date	2017/9/26



■ Feature

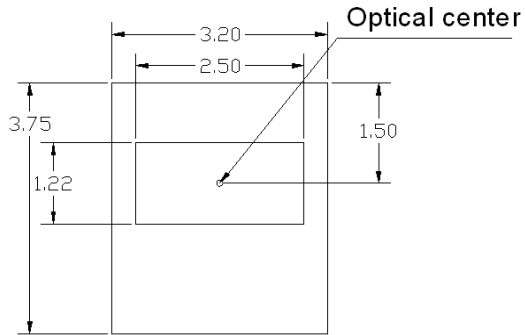
- ✓ White SMD LED (L x W x H) of 3.20x 3.75 x 0.75 mm
- ✓ AEC-Q101 D and IEC 60810 qualification
- ✓ Dice Technology : InGaN
- ✓ Qualified according to JEDEC moisture sensitivity Level 1
- ✓ Environmental friendly ; RoHS compliance
- ✓ Packing : 500/1000 pcs/reel

■ Applications

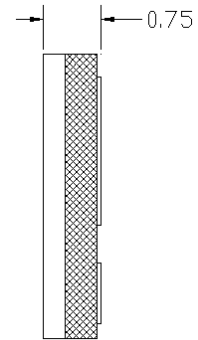
- ✓ DRL
- ✓ Fog light
- ✓ Head lamp

Outline Dimension

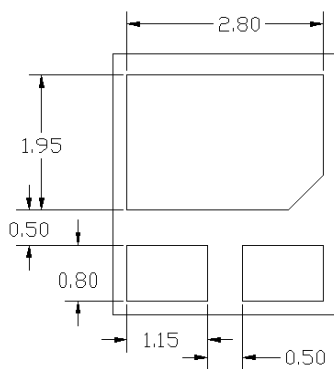
PF06N01 V0
Product Specification



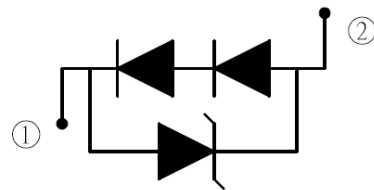
Top view



Side view

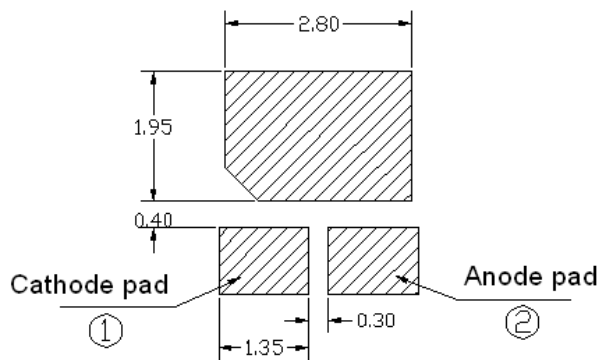


Bottom view



Equivalent Circuit

Recommend Soldering Pad Layout



Unit: mm, Tolerance: $\pm 0.10\text{mm}$

Performance

PF06N01 V0

Product Specification

■ Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage ⁽¹⁾	V_F	IF = 1000 mA	6.0	6.5	7.2	V
Luminous Flux	Φ_V		550	670	800	Lm
View Angle	θ		--	120	--	deg
Electrical Thermal Resistance	$R_{th,elec}$		--	2.5	--	°C/W

- (1) The Forward Voltage tolerance is $\pm 3\%$
- (2) The luminous flux tolerance is $\pm 8\%$
- (3) Thermal resistance is calculated from junction to solder
- (4) Electric and optical data is tested at 25 ms pulse condition
- (5) The Chromaticity Coordinates tolerance is x,y: ± 0.005

■ Absolute Maximum Ratings

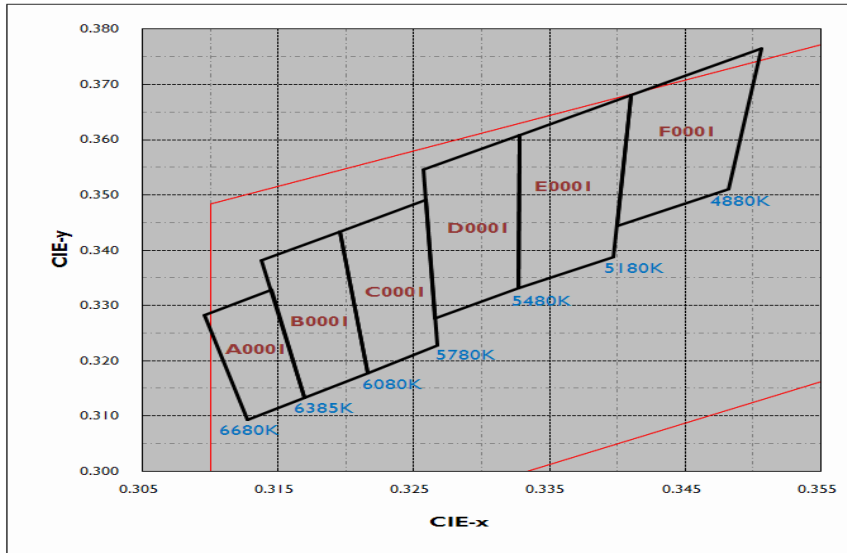
Parameter	Symbol	value	Unit
DC Forward Current ⁽¹⁾	I_F	1200	mA
Power Dissipation	P_D	7.8	W
Storage Temperature	T_{stg}	-40 ~ +125	°C
Operating Temperature	T_{opr}	-40 ~ +125	°C
Junction Temperature	T_J	150	°C
Assembly Temperature	T_{sld}	260 (max. 30sec)	°C
ESD withstand voltage	$V_{ESD(HBM)}$	8	kV

- (1) Proper current rating must be observed to maintain junction temperature below maximum at all time
- (2) IFP Condition: Duty 1/10, Pulse within 10msec

Binning

PF06N01 V0
 Product Specification

Chromaticity Coordinates



Bin code definition

V _F Rank	Luminous Flux Rank	CIE Rank
A	VV	A0001

V _F Rank	Condition	Min.	Max.
A	I _F = 1000 mA Ta = 25°C	6.0	6.4
B		6.4	6.8
C		6.8	7.2

* The Forward Voltage tolerance is ±0.05V

Luminous Flux Rank	Condition	Min.	Max.
VT	I _F = 1000mA Ta = 25°C	550	600
VU		600	650
VV		650	700
VW		700	750
VX		750	800

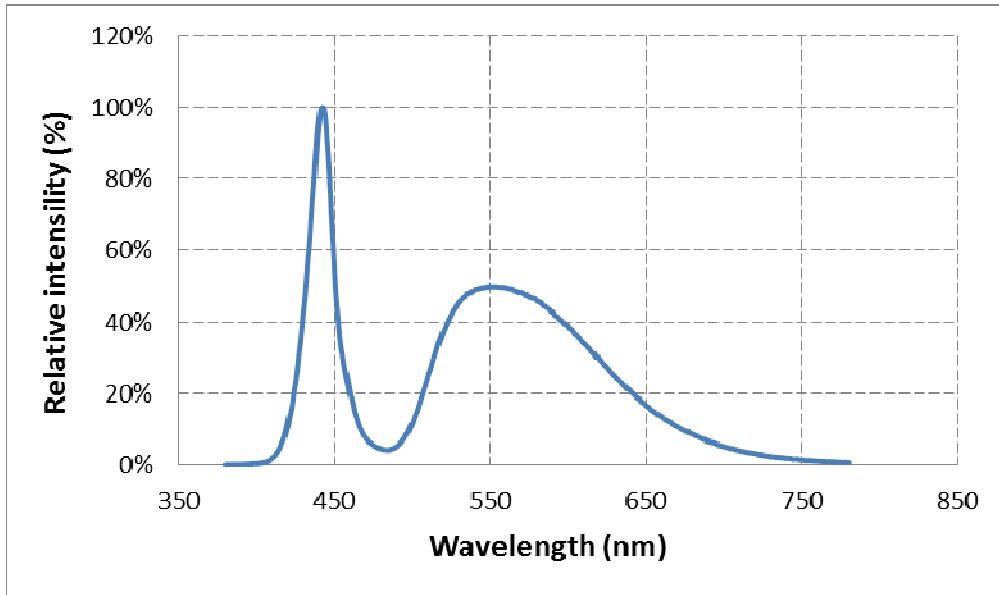
* The luminous intensity tolerance is ± 8%

■ **CIE Rank**

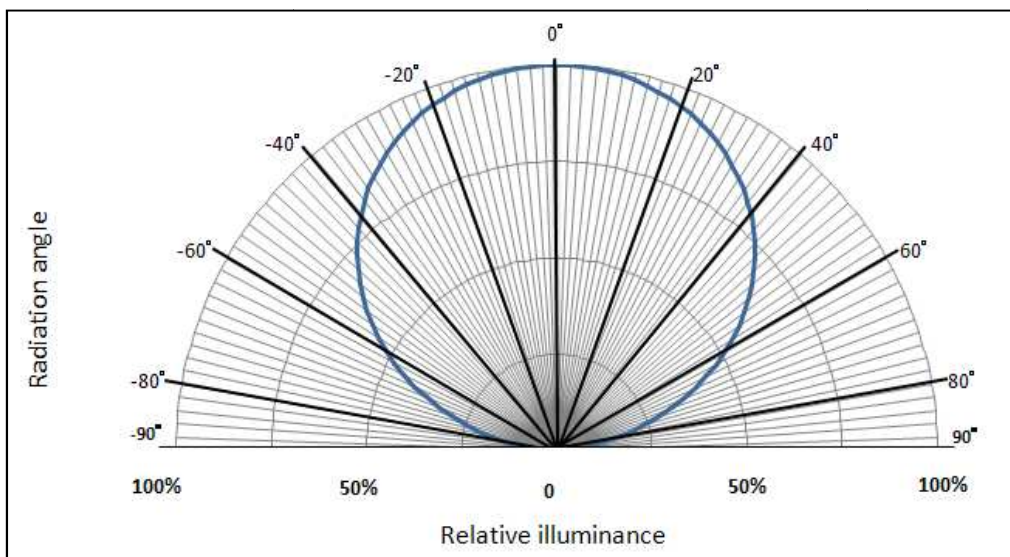
CCT	CIE Rank	CIE X	CIE Y
6385 ~ 6680	A0001	0.3096	0.3283
		0.3145	0.3328
		0.3169	0.3133
		0.3127	0.3093
6080 ~ 6385	B0001	0.3138	0.3381
		0.3195	0.3433
		0.3216	0.3178
		0.3169	0.3133
5780 ~ 6080	C0001	0.3195	0.3433
		0.3259	0.3491
		0.3267	0.3228
		0.3216	0.3178
5480 ~ 5780	D0001	0.3257	0.3546
		0.3328	0.3608
		0.3327	0.3331
		0.3265	0.3276
5180 ~ 5480	E0001	0.3328	0.3608
		0.3410	0.3681
		0.3397	0.3387
		0.3327	0.3331
4880 ~ 5180	F0001	0.3410	0.3681
		0.3506	0.3765
		0.3482	0.3510
		0.3400	0.3443

Color bins are tested at IF = 1000mA 25ms pulse operation condition

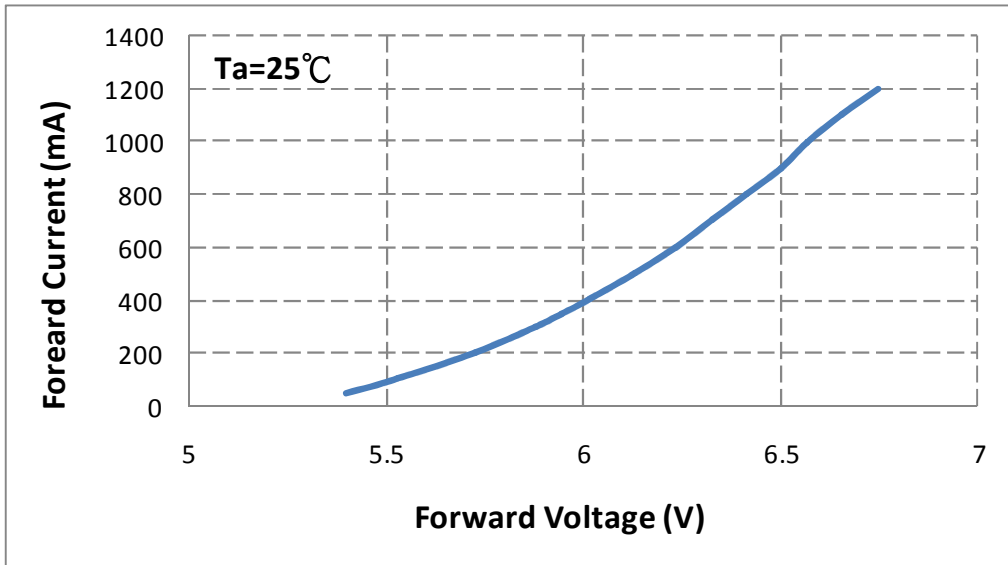
■ Spectrum



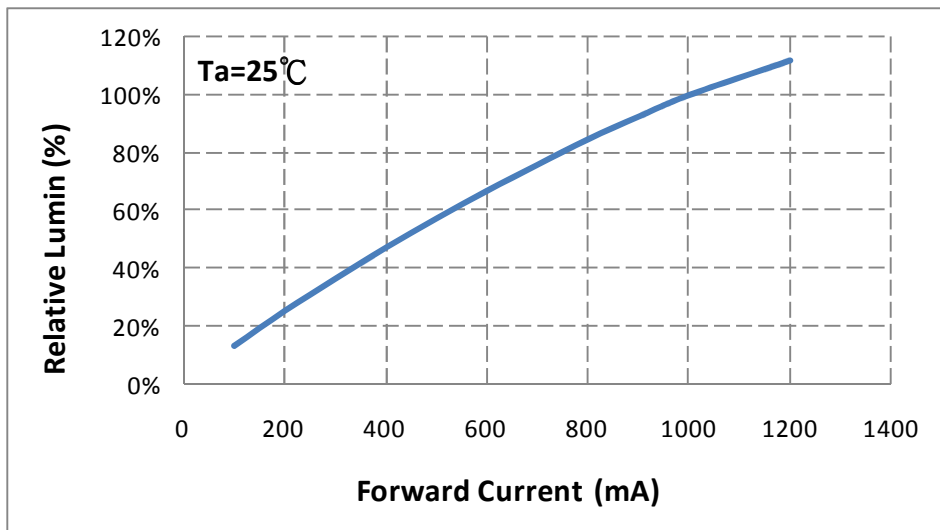
■ Radiation Pattern



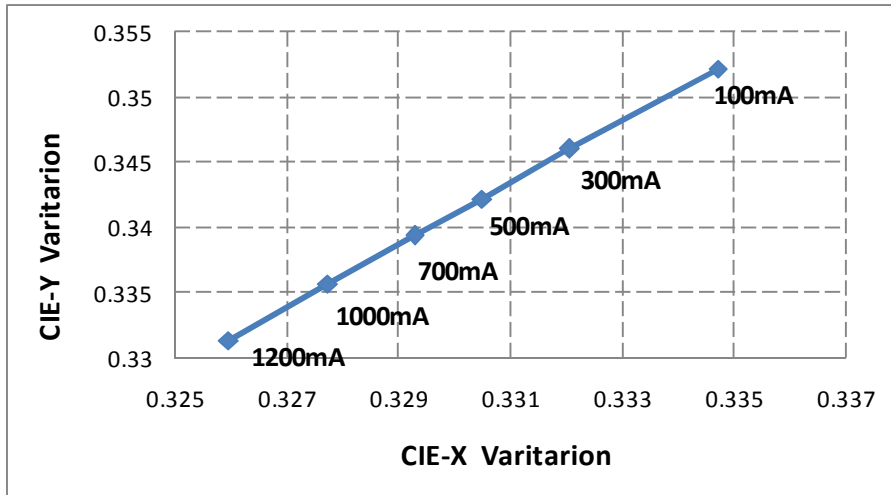
■ Forward Voltage vs. Forward Current



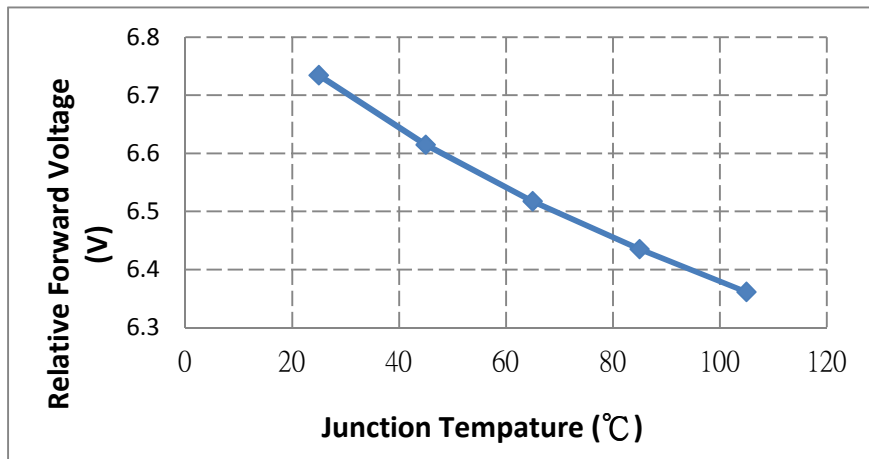
■ Forward Current vs. Relative Luminosity



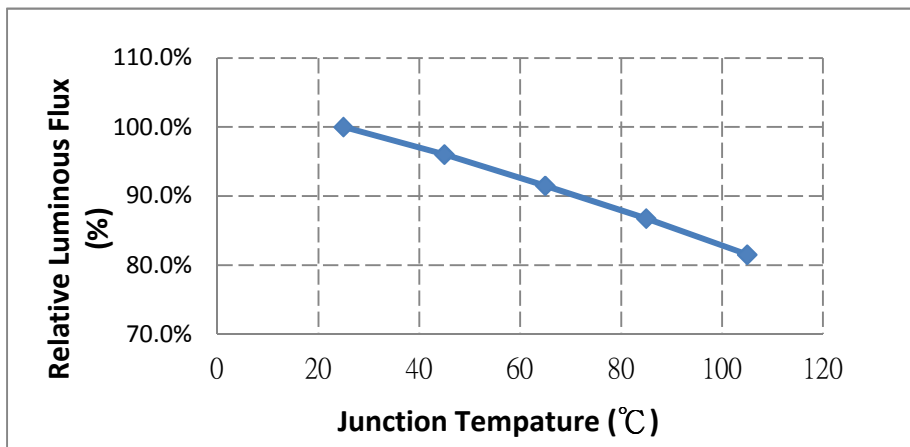
■ Forward Current vs. Chromaticity Coordinate



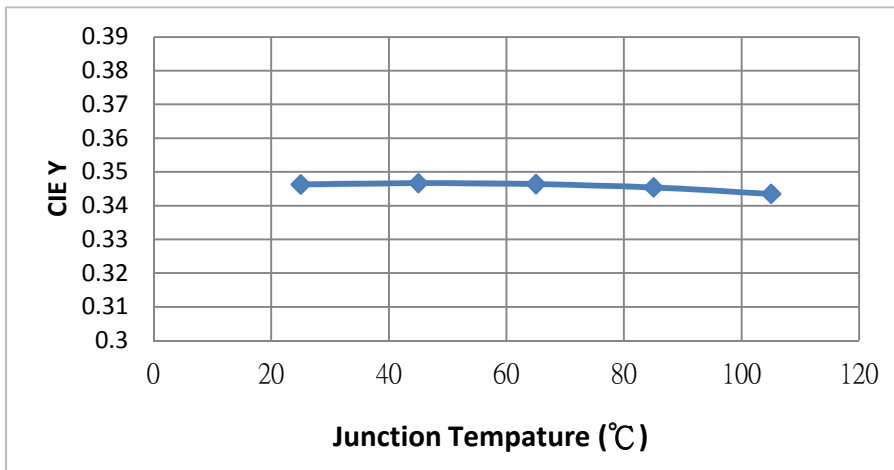
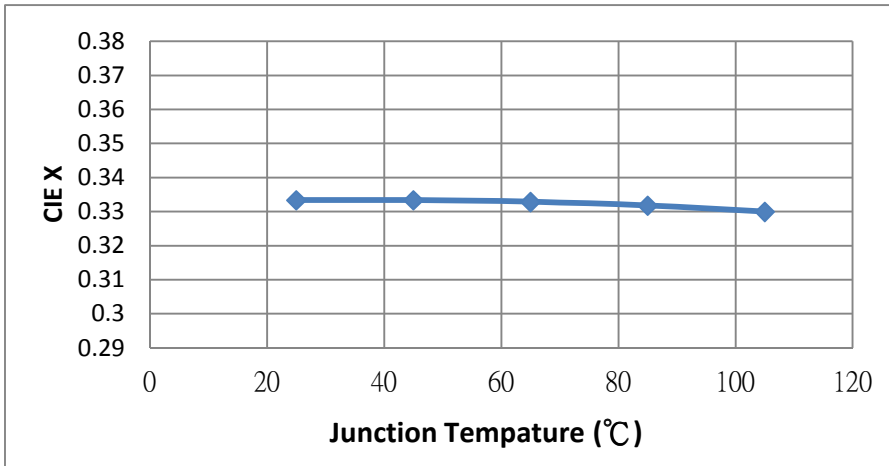
■ Forward Voltage vs. Junction Temperature



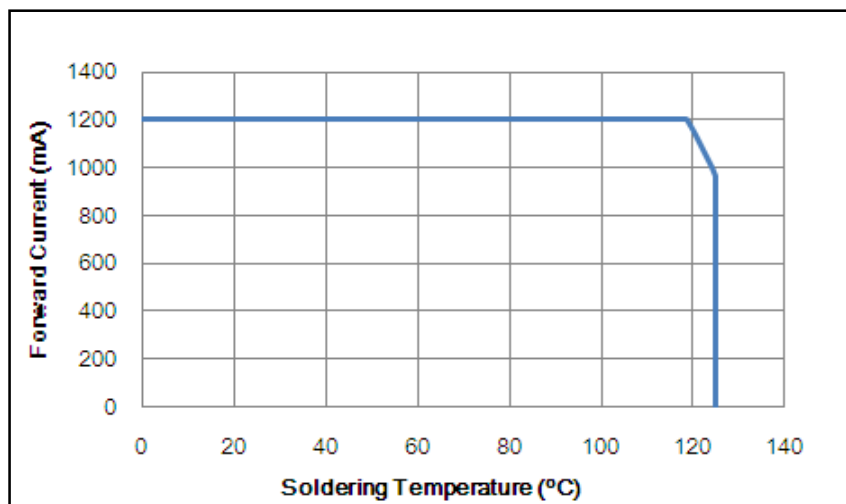
■ Relative Luminous Intensity vs. Junction Temperature



■ Chromaticity vs. Junction Temperature



■ Forward Current Derating Curve



Reliability

PF06N01 V0
 Product Specification

Reliability test

Item	Reference Standard	Condition	Time/Cycle
Thermal shock	JESD22-A106	-40°C to 100 °C, 20min dwell, 5 min transfer time	1000Cycles
Temperature Cycle	AEC-Q101 Rev. D	-55°C to 125 °C 15 minutes dwell at each high and low temperature extreme	1000 cycles
Power and Temperature Cycle	AEC-Q101 Rev. D	-40 °C~ 85 °C, IF=Max Current, Dwell/transfer time=10mins, 20 mins 1,000 cycles , on/off 15,000 cycles	15,000 cycles
MSL Level 1	J-STD-020	85°C/85% RH	168 hours
High Temperature Storage	JESD22-A103	TA=105°C, 1000h	1000hours
Low Temperature Storage	JESD22-A119	TA=-40°C, 1000h	1000hours
High Temperature Operating Life	AEC-Q101 Rev. D	TA=105°C, IF=Max Current	1000hours
Low Temperture Operating Life	JESD22-A108	TA=-40°C, IF=Max Current	1000hours
Temperature Humidity Operating Life	AEC-Q101 Rev. D	85°C, RH=85%, 1000h, IF=Max Current	1000hours
Electrostatic Discharges	AEC-Q101 Rev. D	HBM, X KV,1.5KΩ, 100pF, 3pulses, alternately positive or negative	NA

Item	Reference Standard	Condition	Time
Corrosion robustness	IEC 60068-2-43	(H2S) [25°C / 75 %RH / 10 ppm H ₂ S]	336 hours
	EN60068-2-60	[25 °C / 75 %RH / 200 ppb SO ₂ , 200 ppb NO ₂ ,10 ppb Cl ₂]	504 hours

■ **Judgment Criteria**

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	1000mA	$\Delta V_f < 10 \%$
Luminous Flux	Iv	1000mA	$\Delta I_v < 20 \%$
Delta CIE	CIE-x ,CIE-y	1000mA	$\Delta x,y < 0.01$

Packing

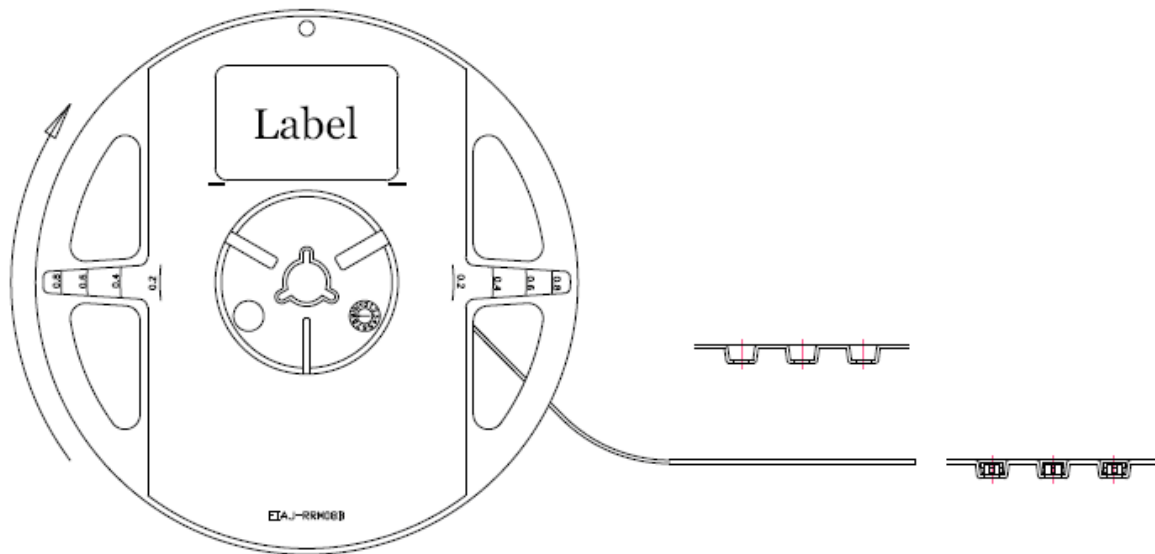
PF06N01 V0

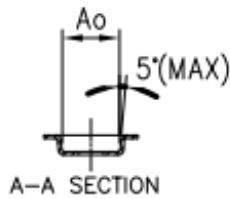
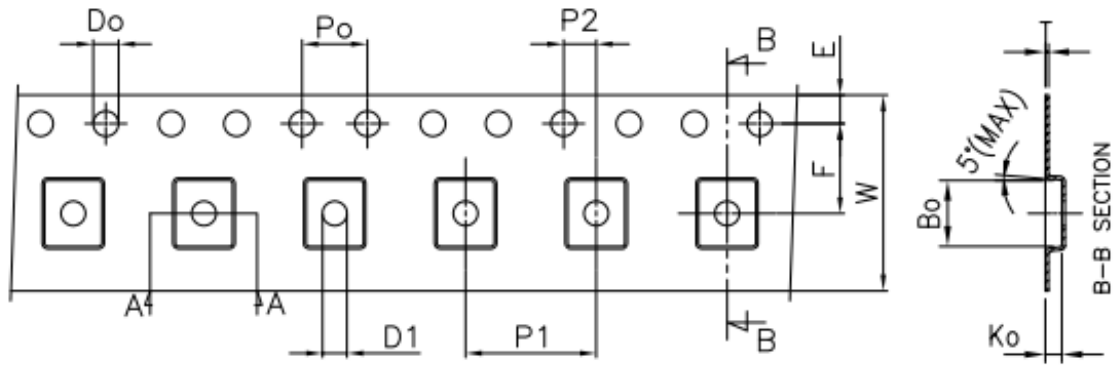
Product Specification

Label



Carrier Taping





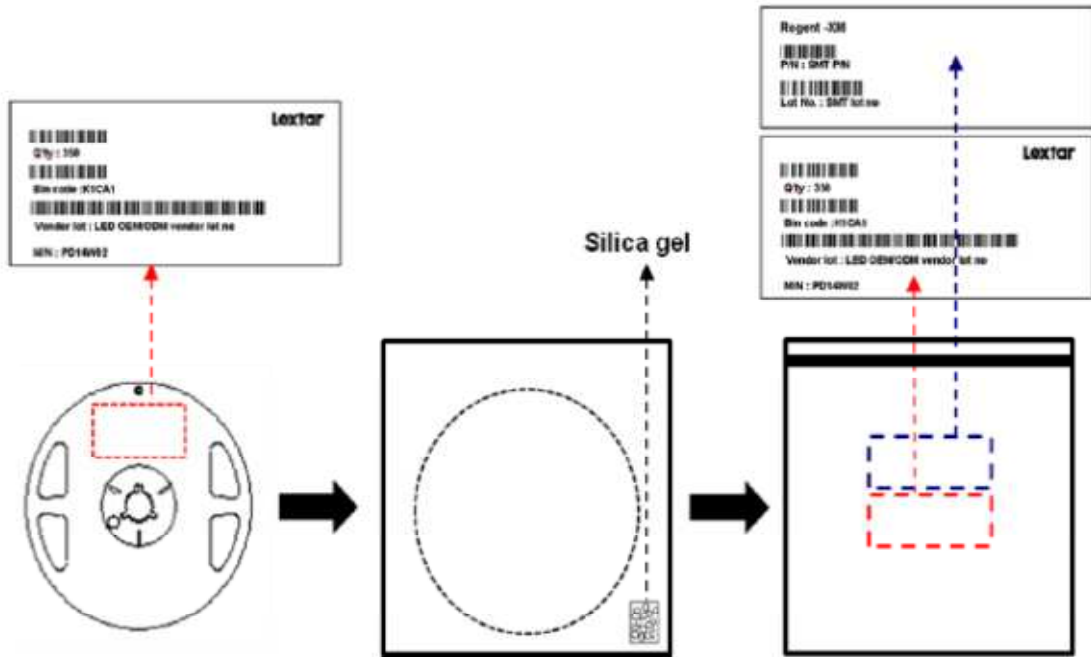
Unit:mm

symbol	Ao	Bo	Ko	Po	P1	P2	T
spec	3.50±0.10	4.05±0.10	1.05±0.10	4.00±0.10	8.00±0.10	2.00±0.05	0.25±0.05
symbol	E	F	Do	D1	W	10Po	
spec	1.75±0.10	5.50±0.05	1.50 ^{+0.10} ₀	1.50±0.10	12.0±0.30	40.00±0.20	

Notice:

1. 10 Sprocket hole pitch cumulative tolerance is ±0.20mm.
2. Carrier camber shall be not more than 1mm per 100mm through a length of 250mm.
3. Ao & Bo measured on a place in the middle of the corner radii.
4. Ko measured from a place on the inside bottom of the pocket to top surface of carrier.
5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
6. Surface resistivity $10^4 \sim 10^8$ ohm/sq.

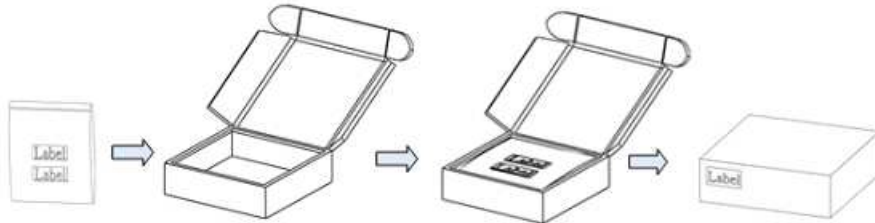
Shield Bag Taping



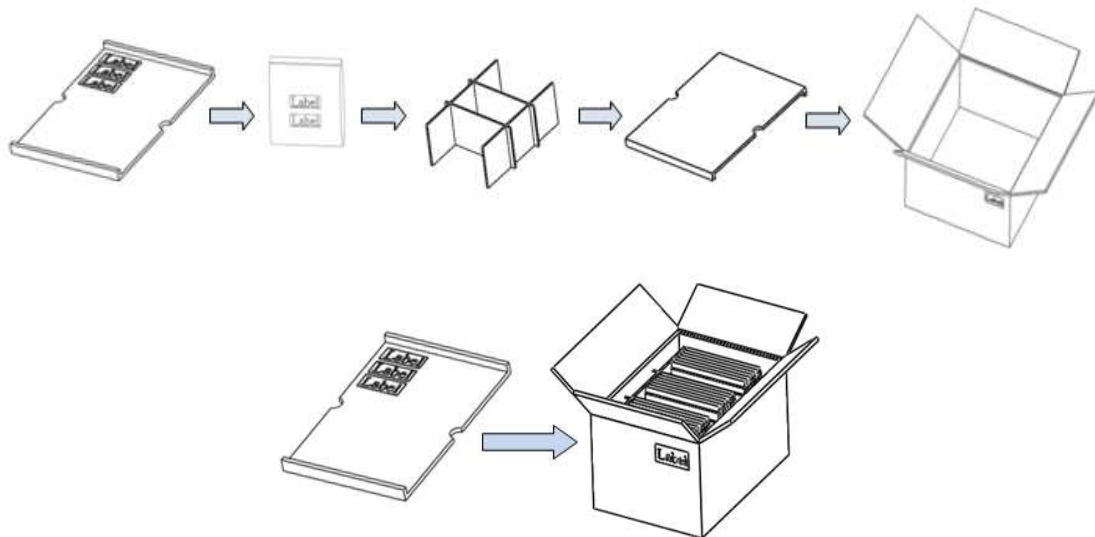
■ Packing Box

Type	Large Box		Medium Box		Small Box	
Dimension	541X511X276mm		385X303X260mm		283X235x70mm	
Maximum Reels	7"X12mm Reel	64/R	7"X12mm Reel	21/R	7"X12mm Reel	4/R
Minimum Reels	7"X12mm Reel	32/R	7"X12mm Reel	9/R	7"X12mm Reel	1/R

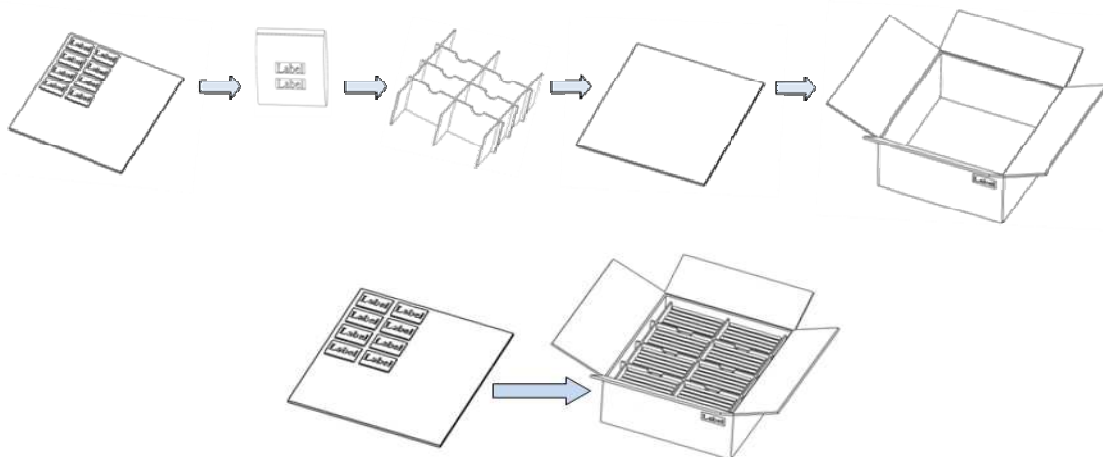
■ Small Box



■ Medium Box



■ Large Box



Precautions

PF06N01 V0
Product Specification

■ Safety Precautions

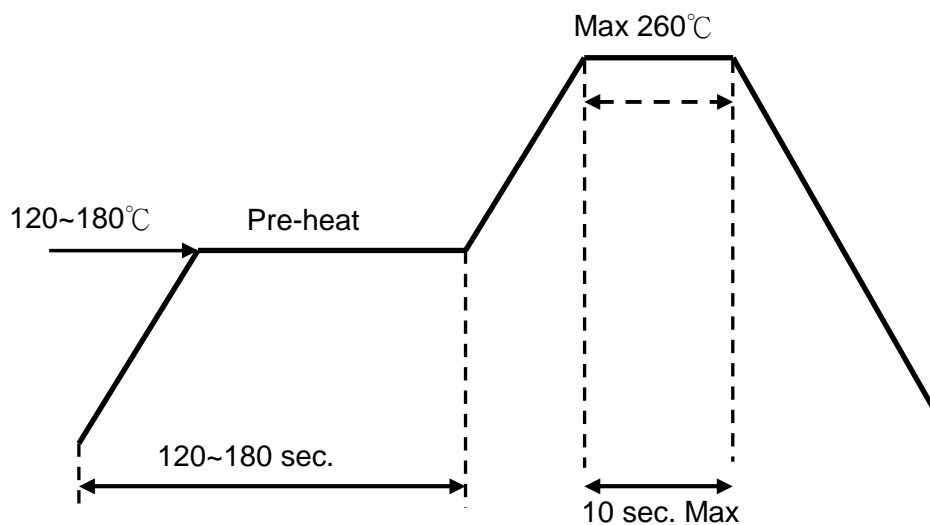
- The LED light output is too strong for human eyes without shield. Prevent eye contact directly more than seconds.
- Ensure operating under maximum rating.

■ Storage

- Before opening the package, the LEDs should storage under 30°C, 60% RH.
- After opening the package bag, the LEDs should be keep under 30°C, 60% RH. Recommend to use within 168 hrs. If unused LEDs remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel. Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.
Bake condition: 60°C, 12hours (One time only).

■ Soldering Notice and Conditions

- When soldering LEDs,
- Do not solder/reflow the same LED over two times.
- Recommend soldering conditions:
Reflow soldering: Pre-heat 150 °C max, 180 sec. max.
Peak 260°C max, 10 sec. max.
- Reflow temperature profile as below: (lead-free solder)



- When soldering, don't put stress on the LEDs
- After LEDs have been soldered, strongly recommend not to repair to keep the LEDs performance.

■ Static Electricity

- LED package is extremely sensitive to static electricity. It's recommended that anti-electrostatic glove and wrist band is necessary when handling the LEDs. All devices are also be grounded properly as well.
- Protection devices design should be considered in the LED driving circuit.

■ Cleaning

- If washing is required, recommend to use alcohol as a solvent.
- Recommend to avoid cleaning the LEDs by ultrasonic. If necessary, pre-test the LED is necessary to confirm whether any damage occur after the process.

Revision History

PF06N01 V0
Product Specification

Date	Contents	Writer	Approved
2015.10.05	Preliminary version	Paul Liu	John Kuo
2017.09.06	Revised edition	SK Chen	Sean Tsai
2017.09.26	Add RA item: Corrosion test	SK Chen	Sean Tsai

Smart Lighting *Amazing Life*

Lextar Electronics Corp. is the leading LED (Light Emitting Diode) maker integrating upper stream epitaxial, middle stream chip, and downstream package, SMT and LED lighting applications. Founded in May, 2008, Lextar is a subsidiary of AU Optronics, the leading TFT-LCD and solar PV manufacturer. Lextar's product applications include lighting and LCD backlight. Lextar's manufacturing sites include Hsinchu and Chunan in Taiwan, and Suzhou in China.

The company turnover in 2010 is 266 million USD.